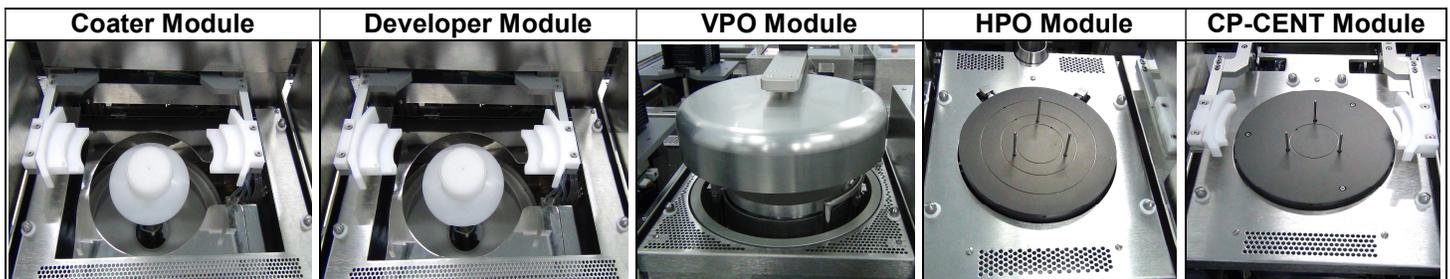


PCT-150RRE TRACK SYSTEM

MASS PRODUCTION WITH DUAL TRACKS (1 COATER, 1 DEVELOPER) TOOL SET

Please contact Sales sales@picotrack.com for more information



Track System Specification	Description																																
System designed	US Standard System																																
System Configuration	<table border="1"> <thead> <tr> <th colspan="8">RANDOM ROBOT ARM # 2</th> </tr> <tr> <th>TRACK #2</th> <th>SEND</th> <th>HPO</th> <th>CP</th> <th>DEV</th> <th>HPO</th> <th>CP-CENT</th> <th>REC</th> </tr> <tr> <th>TRACK #1</th> <th>SEND</th> <th>VPO</th> <th>CP</th> <th>COAT</th> <th>HPO</th> <th>CP-CENT</th> <th>REC</th> </tr> </thead> <tbody> <tr> <td colspan="8">RANDOM ROBOT ARM # 1</td> </tr> </tbody> </table>	RANDOM ROBOT ARM # 2								TRACK #2	SEND	HPO	CP	DEV	HPO	CP-CENT	REC	TRACK #1	SEND	VPO	CP	COAT	HPO	CP-CENT	REC	RANDOM ROBOT ARM # 1							
RANDOM ROBOT ARM # 2																																	
TRACK #2	SEND	HPO	CP	DEV	HPO	CP-CENT	REC																										
TRACK #1	SEND	VPO	CP	COAT	HPO	CP-CENT	REC																										
RANDOM ROBOT ARM # 1																																	
(*Configuration available upon request)																																	
System dimension	Length: 82.5" ; Width: 54" ; Height: 90"																																
Wafer size (workable dual size)	Up to 6" (150mm) or 4" & 6" auto conversion																																
Wafer shape	Round/Square/Rectangular/Triangle/Special																																
Wafer material	Silicon/Sapphire/GaAs/ Ceramic...																																
Wafer sensor	Optical sensor mapping																																
System controller	PC & PLC Controller with Windows OS based																																
Chemical canister cabinet	Solvent (EBR, HMDS, Cleaning...), developer liquid																																
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles																																
Indexer wafer cassettes capacity	4 Indexers																																
Shuttle Robot Arm	2 Robot arms and dual end effectors																																
System Fan Filter Unit (FFU)	optional																																
System SECs/GEM	optional																																
Coater	1 module																																
Catch Cup Set	Fixed position																																
Spindle Unit	Up/down motion																																
Maximum spin speed	6000 rpm																																
Spin motor type	Servo																																
Spin speed accuracy	± 3 rpm																																
Acceleration range	0-50000 rpm/sec																																
Dispense arm accuracy	± 0.1 mm																																
Wafer centering	± 0.1 mm																																
Dispense arm motion control	Stepper motor and driver																																
Dispense arm & nozzles	3x or more (3/16" or 1/4" OD) (Standard)																																
Dispense method	Static and traverse																																
Pre-dispense function	Yes																																
Top/Bottom EBR	Yes																																
Catch-cup rinse(CCR)	Optional																																
Cleaning tip nozzle	Optional																																
Humidity & Temperature control	Optional																																
Photoresist temperature control	Optional (≤ 1°C; 10-50°C range)																																
Developer	1 module																																
Catch Cup Set	Fixed position																																
Spindle Unit	Up/down motion																																
Maximum spin speed	6000 rpm																																
Spin motor type	Servo																																
Spin speed accuracy	± 3 rpm																																
Acceleration range	0-50000 rpm/sec																																
Spin direction	Clockwise (+) & counter clockwise (-)																																
Dispense arm motion control	Stepper motor drive and rotation																																

Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm nozzles	1 Spray+ 1 Stream or 2 spray+ 2 stream (Standard)
Negative developer nozzles	Cone or fan spray with N2 air assist (Upon request)
Developer dispense type	Stream, Puddle, Fan spray, Cone spray....
Dispense method	Static, traverse and sweep
DI water top and back side rinse	Yes
N2 Air Ring back side	Yes
N2 Blow-off top nozzle	Optional
Developer liquid Temp. controller	Optional (≤ 1°C; 10-50°C range)
Vapor Prime Ovent (VPO)	1 module
VPO block type	Aluminum anodized with vacuum slots
VPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	Up to 200°C, Δt: 50°C ≤ 200s
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-200°C)
HMDS prime method	Fume shower on top by N2 pressurized with bubbler
Wafer contact angle	≥ 65° on prime silicon wafer
Contact angle uniformity	≤ 1.5° on prime base silicon wafer
Wafer carrier	3 pins controlled by stepper motor
Bake method	Contact, vacuum & purge bake
Hot Plate Oven (HPO)	3 modules
HPO block type	Aluminum anodized with vacuum slots or standoff proximity
Temperature thermal probe	RTD or TC
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature range	25-250°C, Δt: 50°C ≤ 200s (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
Chill Plate & Centering (CP-CENT)	4 modules
Chill Plate block type	Aluminum anodized with vacuum slots or proximity
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Chill method	Contact
Cooling Water Temperature controller	Optional
Wafer carrier	3 pins controlled by air cylinder
Wafer Centering	Integrated